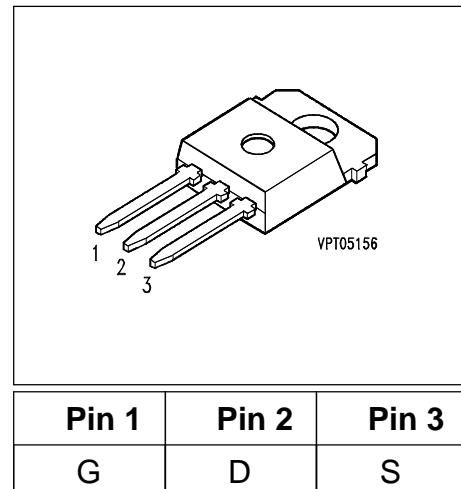


SIPMOS® Power Transistor

- N channel
- Enhancement mode
- Avalanche-rated



Type	V _{DS}	I _D	R _{DS(on)}	Package	Ordering Code
BUZ 332	600 V	8.5 A	0.8 Ω	TO-218 AA	C67078-S3123-A2

Maximum Ratings

Parameter	Symbol	Values	Unit
Continuous drain current $T_C = 33^\circ\text{C}$	I _D	8.5	A
Pulsed drain current $T_C = 25^\circ\text{C}$	I _{Dpuls}	34	
Avalanche current, limited by $T_{j\max}$	I _{AR}	8	
Avalanche energy, periodic limited by $T_{j\max}$	E _{AR}	13	mJ
Avalanche energy, single pulse $I_D = 8 \text{ A}, V_{DD} = 50 \text{ V}, R_{GS} = 25 \Omega$ $L = 16.3 \text{ mH}, T_j = 25^\circ\text{C}$	E _{AS}	570	
Gate source voltage	V _{GS}	± 20	V
Power dissipation $T_C = 25^\circ\text{C}$	P _{tot}	150	W
Operating temperature	T _j	-55 ... + 150	°C
Storage temperature	T _{stg}	-55 ... + 150	
Thermal resistance, chip case	R _{thJC}	≤ 0.83	K/W
Thermal resistance, chip to ambient	R _{thJA}	75	
DIN humidity category, DIN 40 040		E	
IEC climatic category, DIN IEC 68-1		55 / 150 / 56	

Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Static Characteristics

Drain- source breakdown voltage $V_{GS} = 0 \text{ V}, I_D = 0.25 \text{ mA}, T_j = 25^\circ\text{C}$	$V_{(\text{BR})\text{DSS}}$	600	-	-	V
Gate threshold voltage $V_{GS}=V_{DS}, I_D = 1 \text{ mA}$	$V_{GS(\text{th})}$	2.1	3	4	
Zero gate voltage drain current $V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 25^\circ\text{C}$ $V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 125^\circ\text{C}$	I_{DSS}	- -	0.1 10	1 100	μA
Gate-source leakage current $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$	I_{GSS}	-	10	100	nA
Drain-Source on-resistance $V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	$R_{\text{DS}(\text{on})}$	-	0.7	0.8	Ω

Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Dynamic Characteristics

Transconductance $V_{DS} \geq 2 * I_D * R_{DS(on)max}, I_D = 5 \text{ A}$	g_{fs}	5	8.5	-	S
Input capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{iss}	-	1400	2100	pF
Output capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{oss}	-	180	270	
Reverse transfer capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{rss}	-	65	100	
Turn-on delay time $V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$ $R_{GS} = 50 \Omega$	$t_{d(on)}$	-	20	30	ns
Rise time $V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$ $R_{GS} = 50 \Omega$	t_r	-	70	110	
Turn-off delay time $V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$ $R_{GS} = 50 \Omega$	$t_{d(off)}$	-	250	330	
Fall time $V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$ $R_{GS} = 50 \Omega$	t_f	-	80	100	

Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

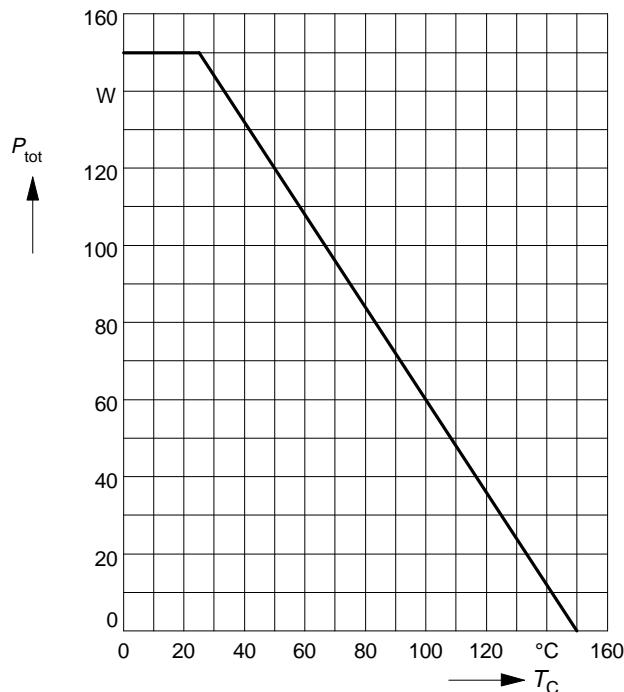
Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Reverse Diode

Inverse diode continuous forward current $T_C = 25^\circ\text{C}$	I_S	-	-	8.5	A
Inverse diode direct current,pulsed $T_C = 25^\circ\text{C}$	I_{SM}	-	-	34	
Inverse diode forward voltage $V_{GS} = 0 \text{ V}, I_F = 16 \text{ A}$	V_{SD}	-	1.1	1.2	V
Reverse recovery time $V_R = 100 \text{ V}, I_F=I_S, di_F/dt = 100 \text{ A}/\mu\text{s}$	t_{rr}	-	480	-	ns
Reverse recovery charge $V_R = 100 \text{ V}, I_F=I_S, di_F/dt = 100 \text{ A}/\mu\text{s}$	Q_{rr}	-	6.5	-	μC

Power dissipation

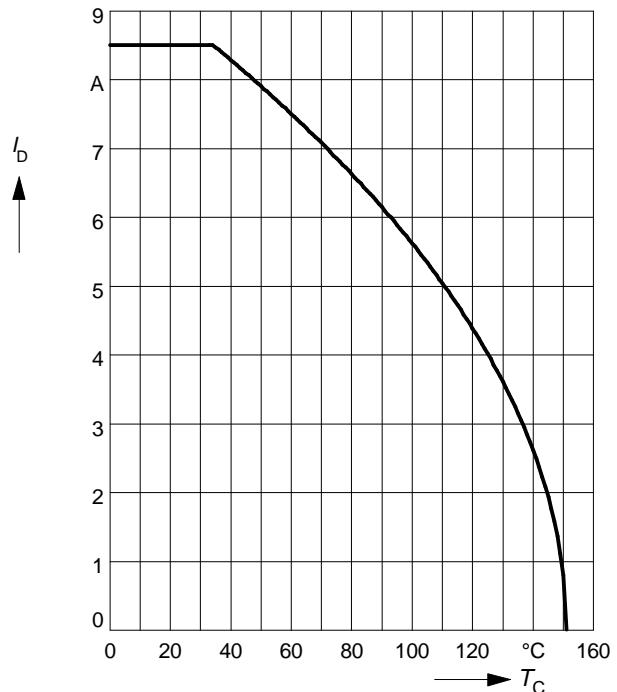
$$P_{\text{tot}} = f(T_C)$$



Drain current

$$I_D = f(T_C)$$

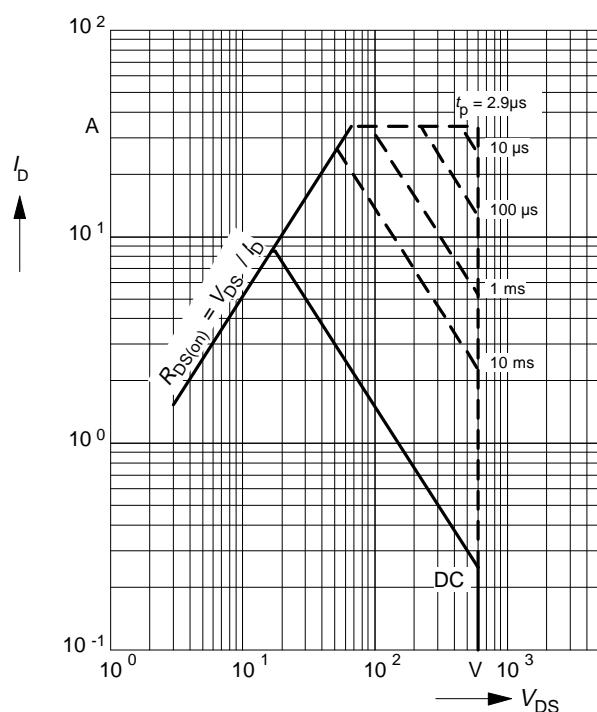
parameter: $V_{GS} \geq 10$ V



Safe operating area

$$I_D = f(V_{DS})$$

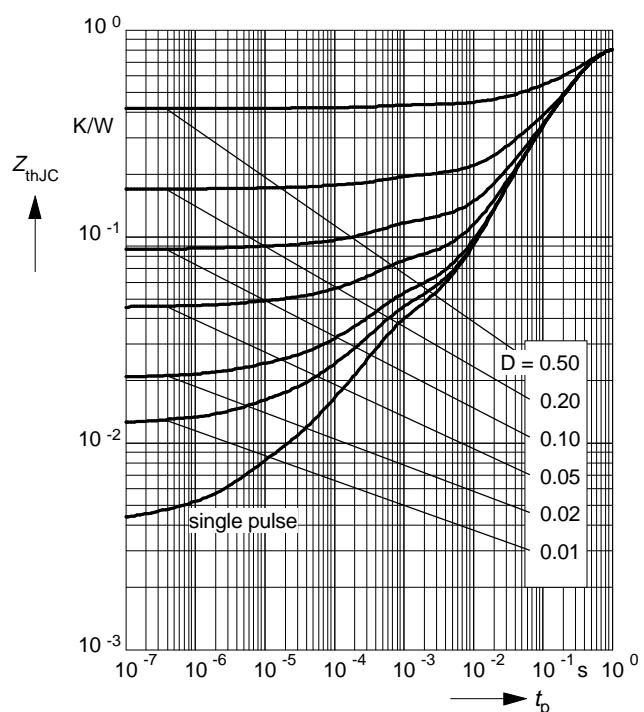
parameter: $D = 0.01$, $T_C = 25^\circ\text{C}$



Transient thermal impedance

$$Z_{\text{thJC}} = f(t_p)$$

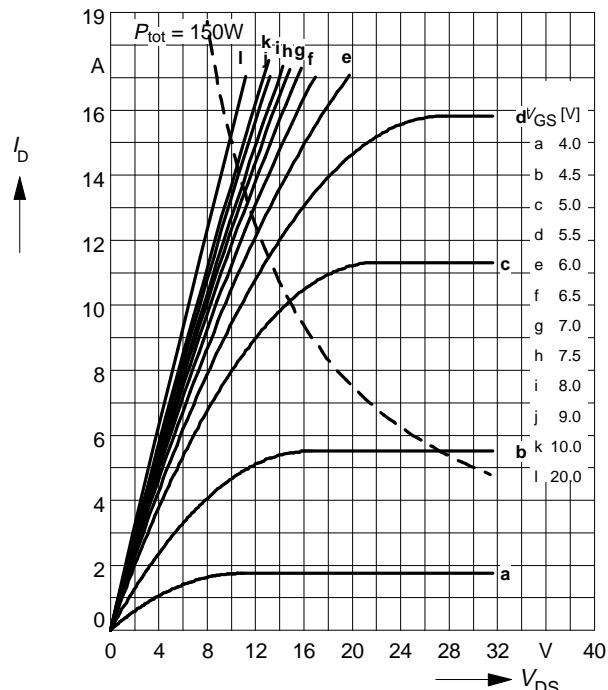
parameter: $D = t_p / T$



Typ. output characteristics

$$I_D = f(V_{DS})$$

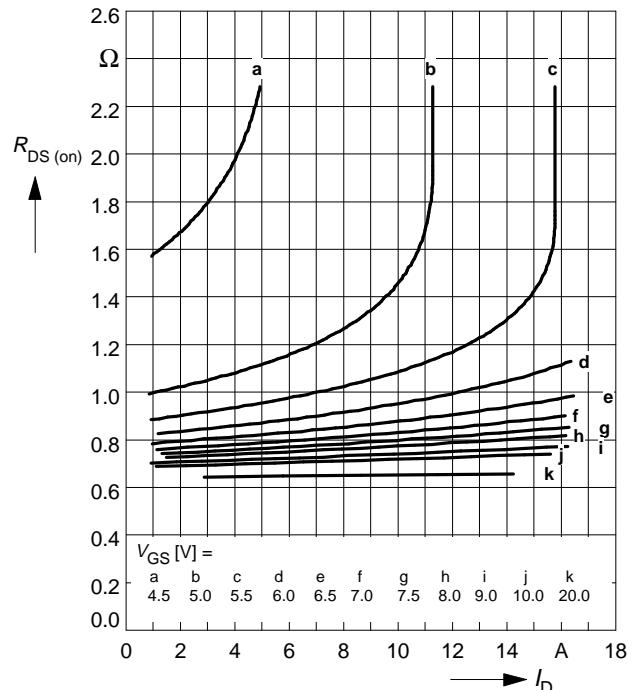
parameter: $t_p = 80 \mu\text{s}$



Typ. drain-source on-resistance

$$R_{DS(on)} = f(I_D)$$

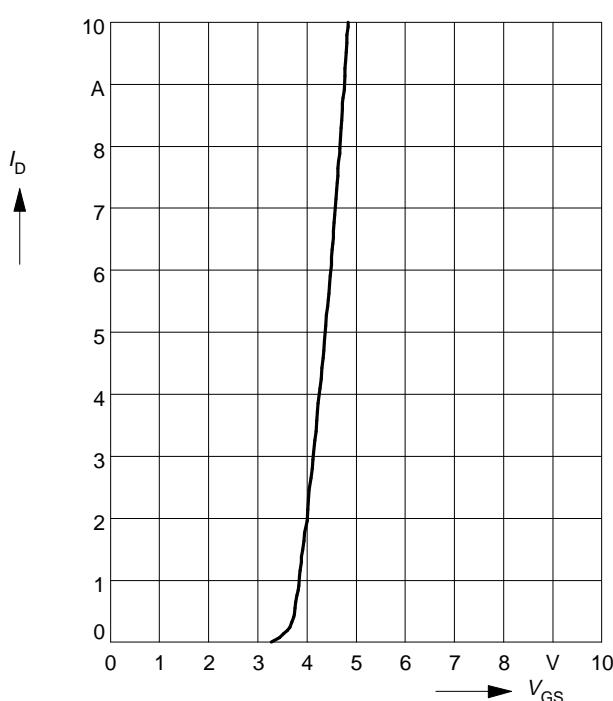
parameter: V_{GS}



Typ. transfer characteristics $I_D = f(V_{GS})$

parameter: $t_p = 80 \mu\text{s}$

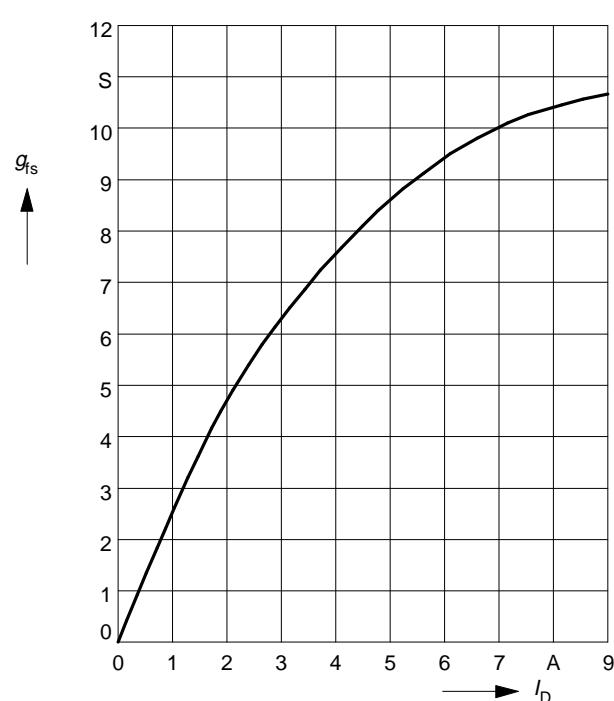
$$V_{DS} \geq 2 \times I_D \times R_{DS(on)\max}$$



Typ. forward transconductance $g_{fs} = f(I_D)$

parameter: $t_p = 80 \mu\text{s}$,

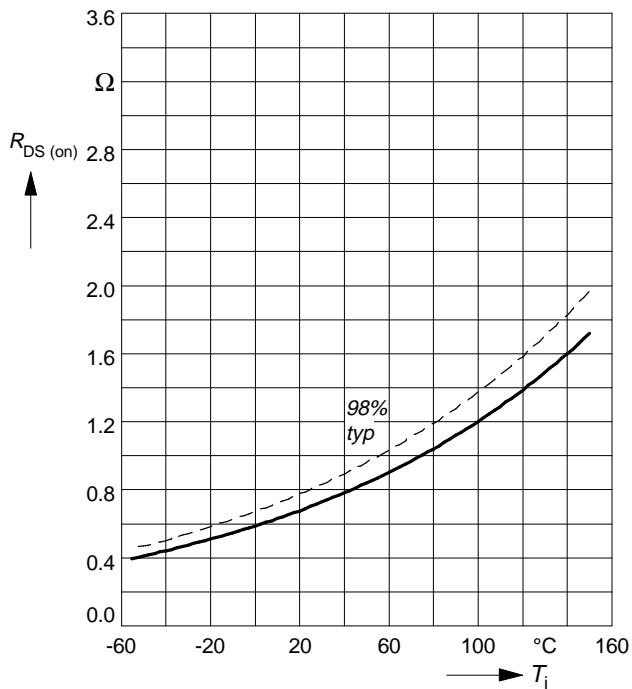
$$V_{DS} \geq 2 \times I_D \times R_{DS(on)\max}$$



Drain-source on-resistance

$$R_{DS(on)} = f(T_j)$$

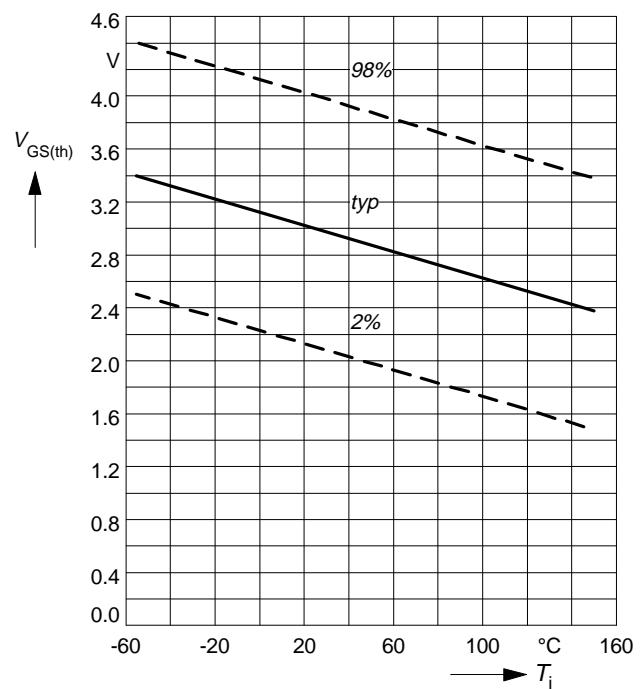
parameter: $I_D = 5 \text{ A}$, $V_{GS} = 10 \text{ V}$



Gate threshold voltage

$$V_{GS(th)} = f(T_j)$$

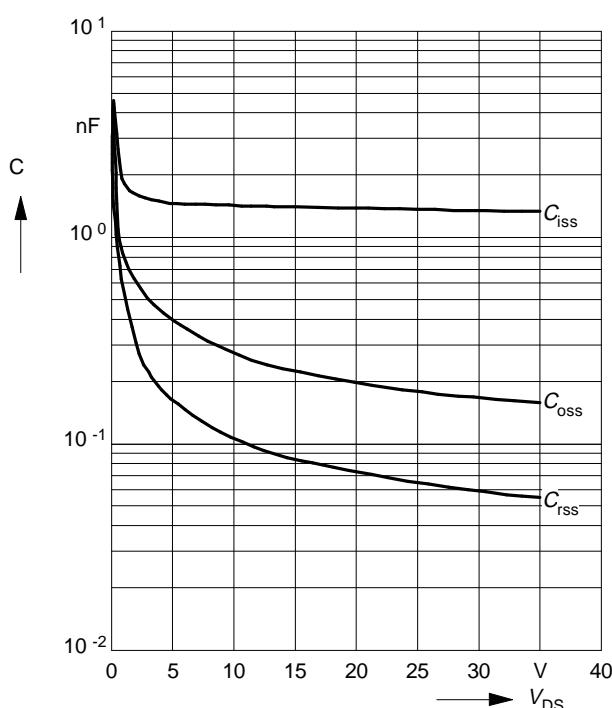
parameter: $V_{GS} = V_{DS}$, $I_D = 1 \text{ mA}$



Typ. capacitances

$$C = f(V_{DS})$$

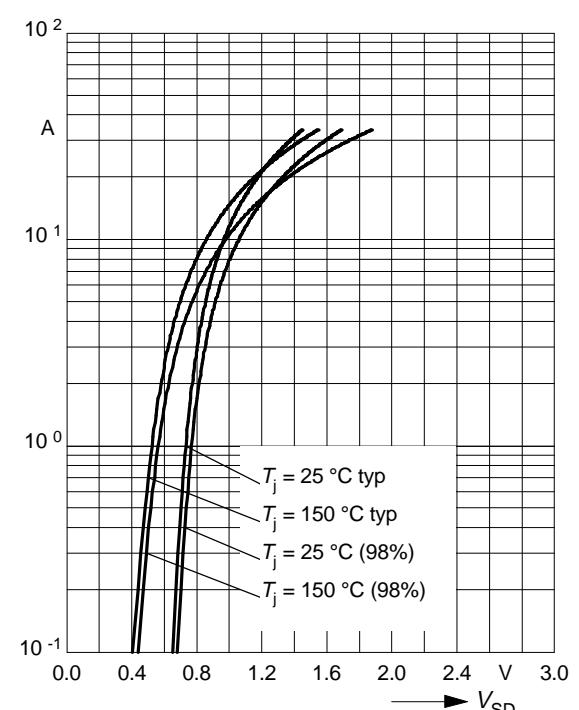
parameter: $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$



Forward characteristics of reverse diode

$$I_F = f(V_{SD})$$

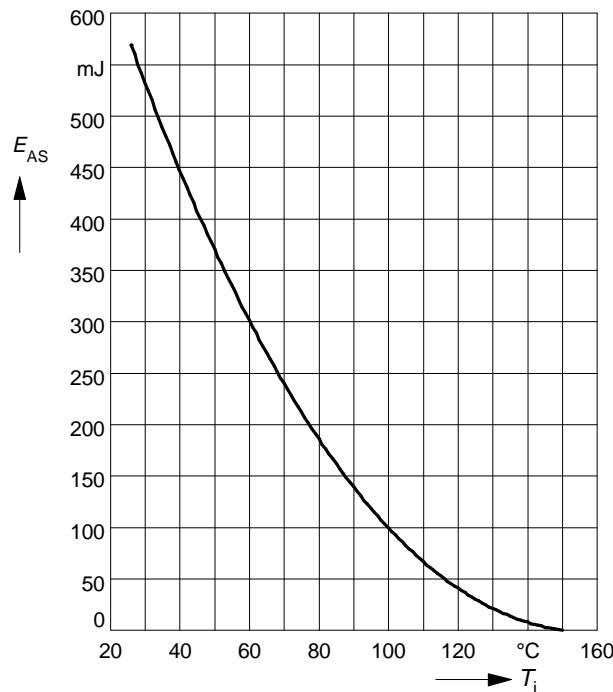
parameter: T_j , $t_p = 80 \mu\text{s}$



Avalanche energy $E_{AS} = f(T_j)$

parameter: $I_D = 8 \text{ A}$, $V_{DD} = 50 \text{ V}$

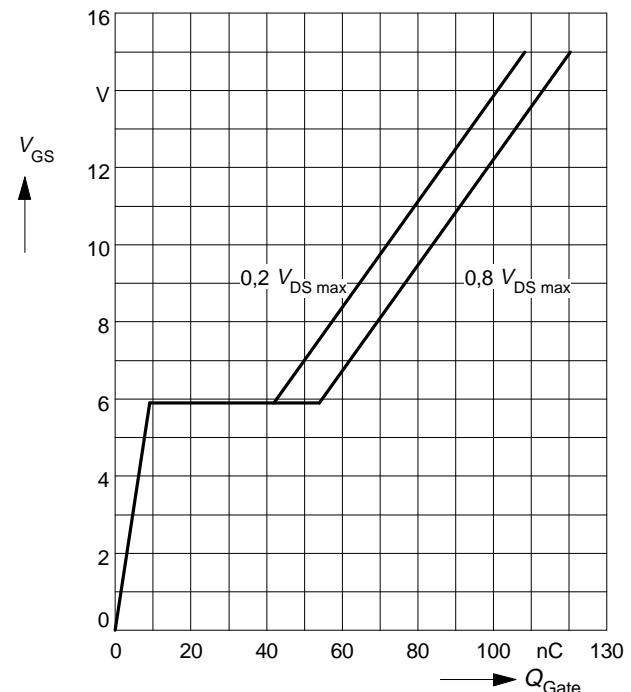
$R_{GS} = 25 \Omega$, $L = 16.3 \text{ mH}$



Typ. gate charge

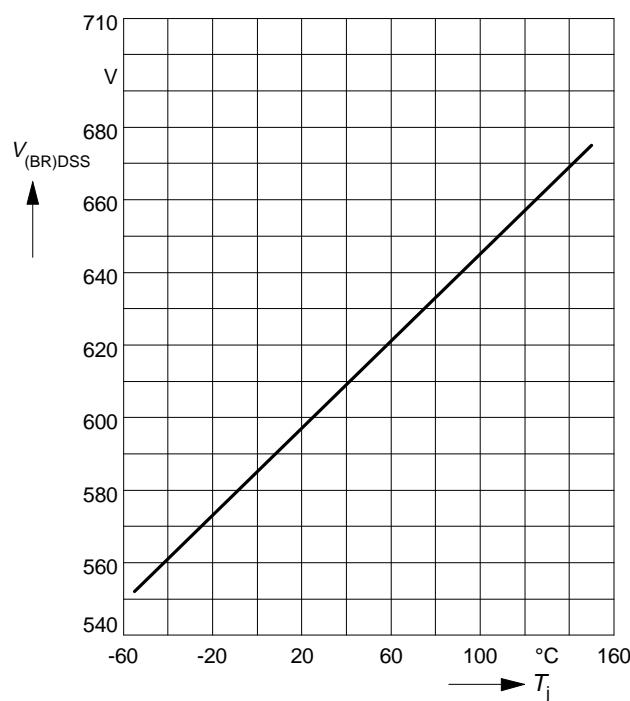
$V_{GS} = f(Q_{Gate})$

parameter: $I_{D \text{ puls}} = 12 \text{ A}$



Drain-source breakdown voltage

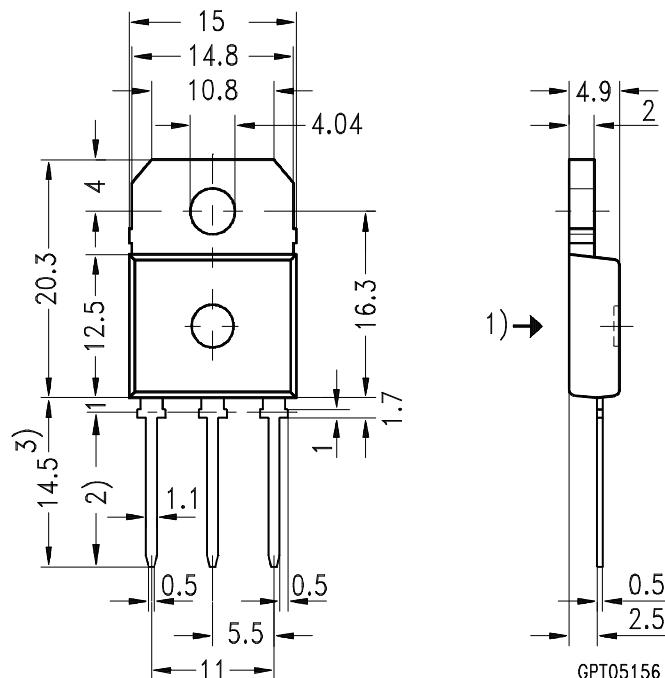
$V_{(BR)DSS} = f(T_j)$



Package Outlines

TO-218 AA

Dimension in mm



- 1) punch direction, burr max. 0.04
- 2) dip tinning
- 3) max. 15.5 by dip tinning press burr max. 0.05